

12 said inner and outer [sides] edges being uniformly spaced apart defining
13 therebetween a chip-support zone for the frame having defined dimensions.

14 said [zone being] outer edges of the sidebars being recessed from the outer edges of
15 the chip such that the frame is smaller a corresponding dimension of the chip, so as to avoid
16 formation of a fillet of chip attach material proximate to the outer edges of the chip when the chip is
17 attached to the frame, [each sidebar having an upper chip-supporting surface for engaging the bottom
18 surface of the chip].

20 Cancel claim 9 without prejudice.

22 16. (New) A lead frame, for an integrated circuit chip having a frame engaging
23 bottom surface for attachment to the frame by means of a chip attach material, said chip being
24 formed with outer edges having defined dimensions, said frame comprising:

26 a unitary apertured frame having a chip-supporting surface for engaging the bottom
27 of the surface of the chip with the chip attach material therebetween, said frame having an outer
28 edge, and an aperture formed with an inner edge defining the through central aperture,
29 edge,

30 said inner and outer edges being uniformly spaced apart defining therebetween a
31 chip-support zone having defined dimensions,

33 said outer edge of the apertured frame being recessed from the outer edges of the
34 chip such that the frame is smaller than a corresponding dimension of the chip, so as to avoid
35 formation of a fillet of chip attach material to the outer edges of the chip when the chip is attached to
36 the apertured frame.

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